

Power MOSFET

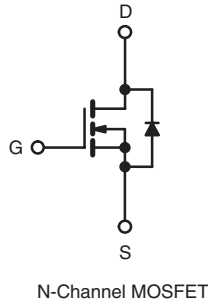
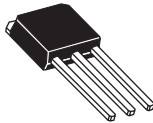
PRODUCT SUMMARY

V_{DS} (V)	60	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$	0.10
Q_g (Max.) (nC)	25	
Q_{gs} (nC)	5.8	
Q_{gd} (nC)	11	
Configuration	Single	

PAK
(TO-252)



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(TO-251)



FEATURES

- Dynamic dV/dt Rating
- Surface Mount (IRFR020/SiHFR020)
- Available in Tape and Reel
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead (Pb)-free Available



Available
RoHS*
COMPLIANT

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The PAK is designed for surface mounting using vapor phase, infrared, or wave soldering techniques.

ORDERING INFORMATION

Package	PAK (TO-252)	PAK (TO-252)	PAK (TO-251)
Lead (Pb)-free	IRFR020PbF	IRFR020TRPbF ^a	IRFU020PbF
	SiHFR020-E3	SiHFR020T-E3 ^a	SiHFU020-E3
SnPb	IRFR020	IRFR020TR ^a	IRFU020
	SiHFR020	SiHFR020T ^a	SiHFU020

Note

a. See device orientation.

ABSOLUTE MAXIMUM RATINGS $T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	$T_C = 25\text{ }^\circ\text{C}$	A
		$T_C = 100\text{ }^\circ\text{C}$	
Pulsed Drain Current ^a	I_{DM}	56	W/ $^\circ\text{C}$
Linear Derating Factor		0.33	
Linear Derating Factor (PCB Mount) ^e		0.020	
Single Pulse Avalanche Energy ^b	E_{AS}	91	mJ
Maximum Power Dissipation	P_D	$T_C = 25\text{ }^\circ\text{C}$	W
Maximum Power Dissipation (PCB Mount) ^e		$T_A = 25\text{ }^\circ\text{C}$	
Peak Diode Recovery dV/dt ^c	dV/dt	5.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s	260 ^d	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 25\text{ V}$, starting $T_J = 25\text{ }^\circ\text{C}$, $L = 541\text{ }\mu\text{H}$, $R_G = 25\text{ }\Omega$, $I_{AS} = 14\text{ A}$ (see fig. 12).
- $I_{SD} \leq 17\text{ A}$, $dI/dt \leq 110\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^\circ\text{C}$.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).

* Pb containing terminations are not RoHS compliant, exemptions may apply

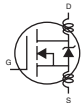
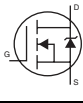
THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	-	110	°C/W
Maximum Junction-to-Ambient (PCB Mount) ^a	R_{thJA}	-	-	50	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	-	3.0	

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		60	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.073	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V		-	-	25	μA
		V _{DS} = 48 V, V _{GS} = 0 V, T _J = 125 °C		-	-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 8.4 A ^b	-	-	0.10	Ω
Forward Transconductance	g _{fs}	V _{DS} = 25 V, I _D = 8.4 A		6.2	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	640	-	pF
Output Capacitance	C _{oss}			-	360	-	
Reverse Transfer Capacitance	C _{rss}			-	79	-	
Total Gate Charge	Q _g	V _{GS} = 10 V	I _D = 17 A, V _{DS} = 48 V, see fig. 6 and 13 ^b	-	-	25	nC
Gate-Source Charge	Q _{gs}			-	-	5.8	
Gate-Drain Charge	Q _{gd}			-	-	11	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 30 V, I _D = 17 A, R _G = 18 Ω, R _D = 1.7 Ω, see fig. 10 ^b		-	13	-	ns
Rise Time	t _r			-	58	-	
Turn-Off Delay Time	t _{d(off)}			-	25	-	
Fall Time	t _f			-	42	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact ^c 		-	4.5	-	nH
Internal Source Inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	14	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	56	
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = 14 A, V _{GS} = 0 V ^b		-	-	1.5	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 17 A, dI/dt = 100 A/μs ^b		-	88	180	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	0.29	0.64	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

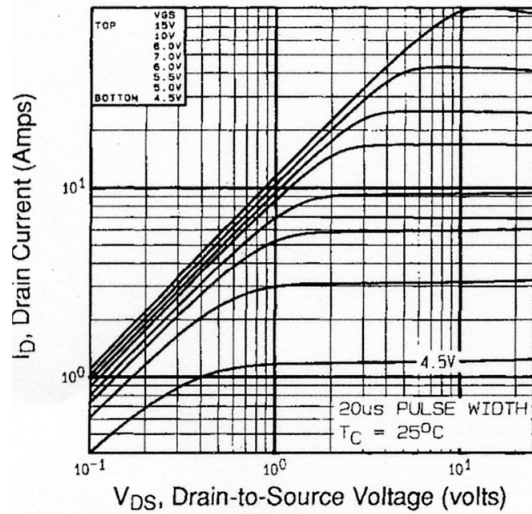


Fig. 1 - Typical Output Characteristics, $T_C = 25^\circ\text{C}$

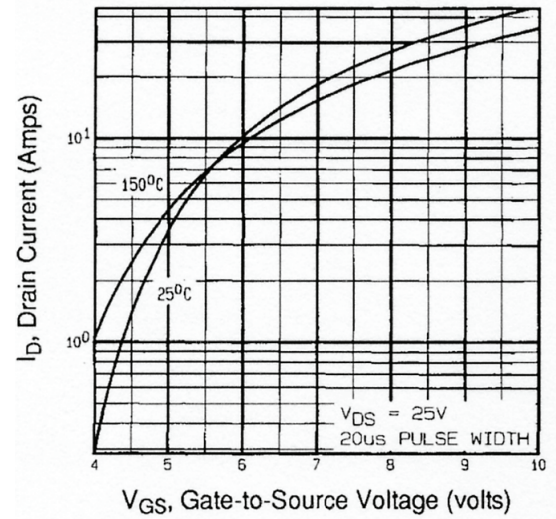


Fig. 3 - Typical Transfer Characteristics

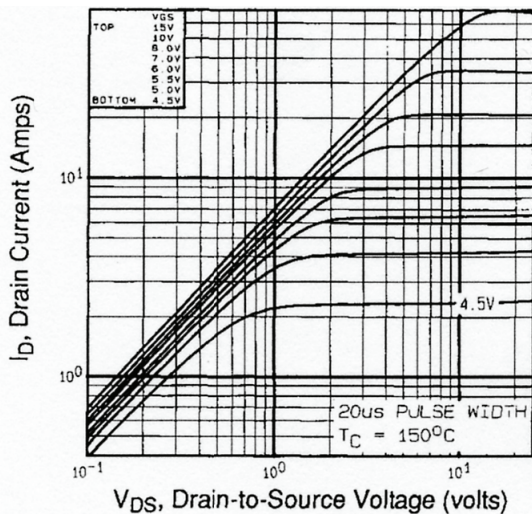


Fig. 2 - Typical Output Characteristics, $T_C = 150^\circ\text{C}$

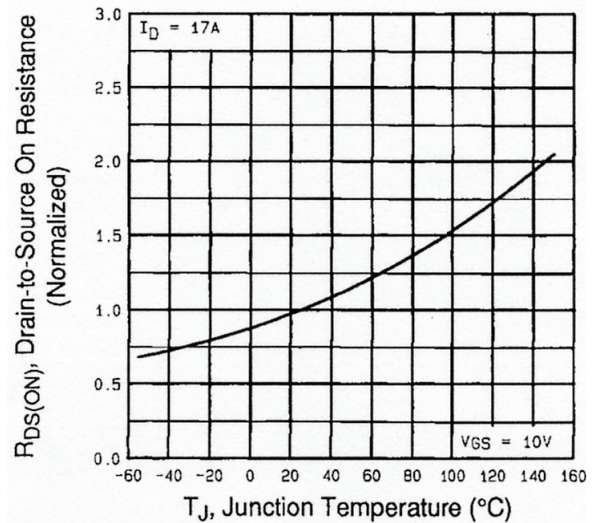
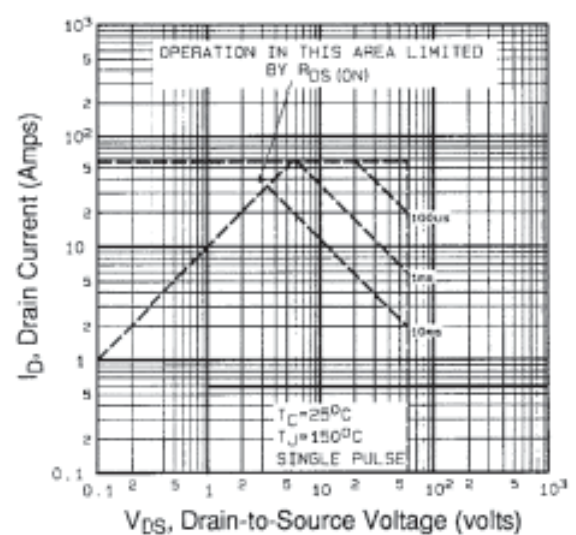
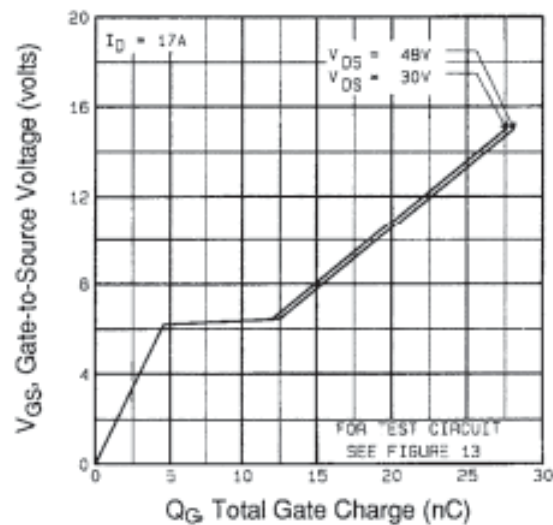
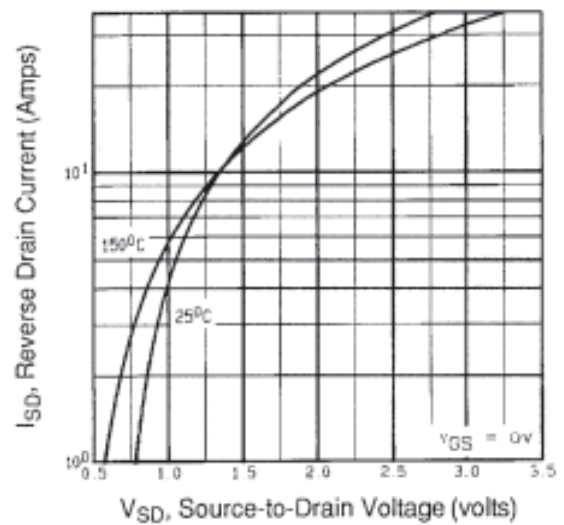
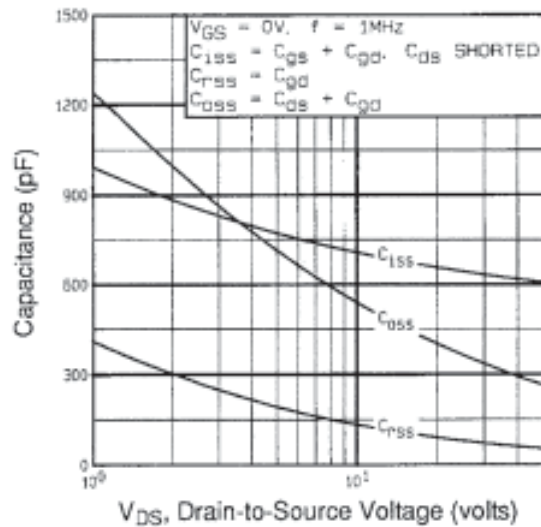


Fig. 4 - Normalized On-Resistance vs. Temperature



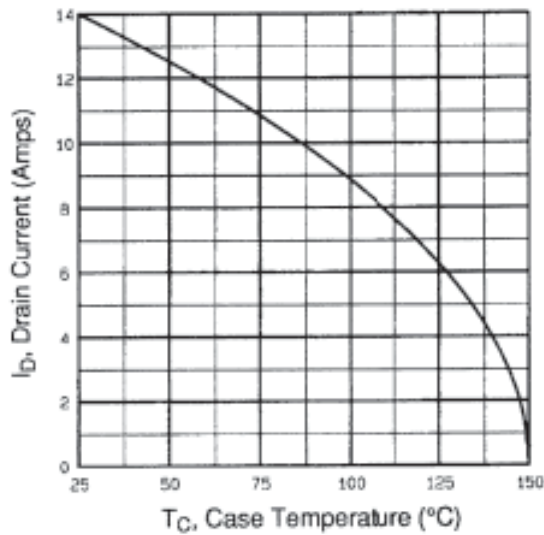


Fig. 9 - Maximum Drain Current vs. Case Temperature

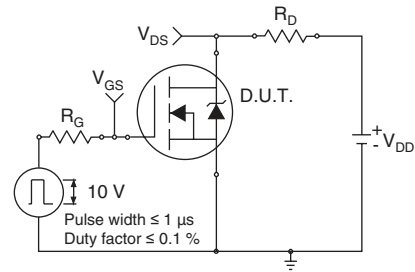


Fig. 10a - Switching Time Test Circuit

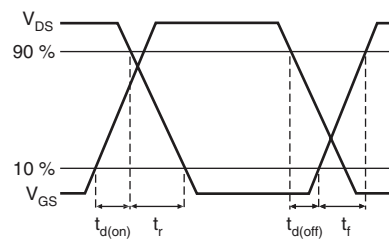


Fig. 10b - Switching Time Waveforms

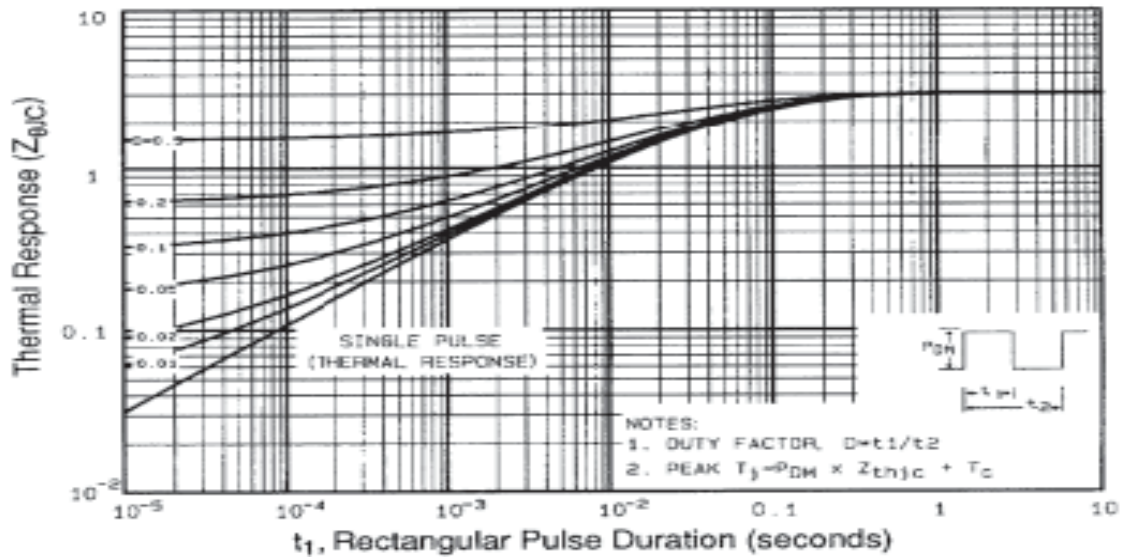


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

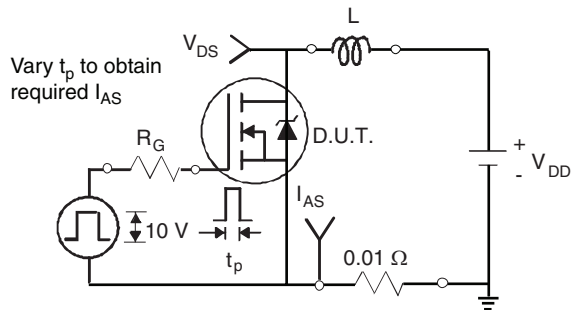


Fig. 12a - Unclamped Inductive Test Circuit

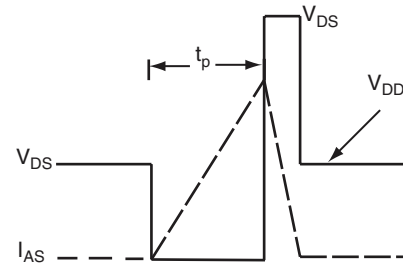


Fig. 12b - Unclamped Inductive Waveforms

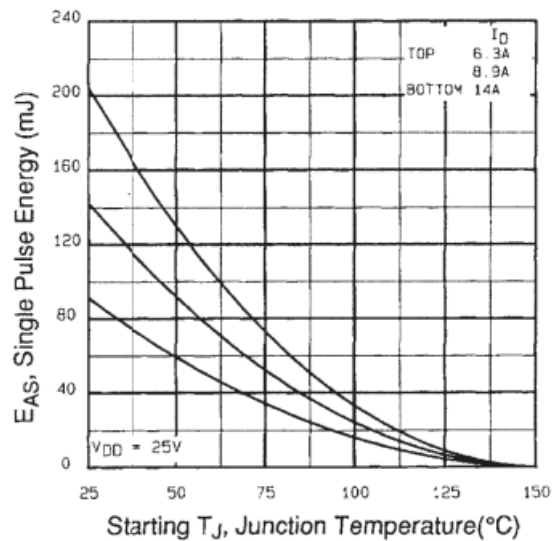


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

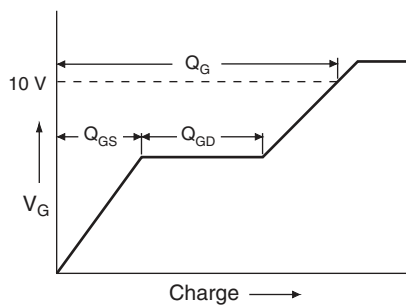


Fig. 13a - Basic Gate Charge Waveform

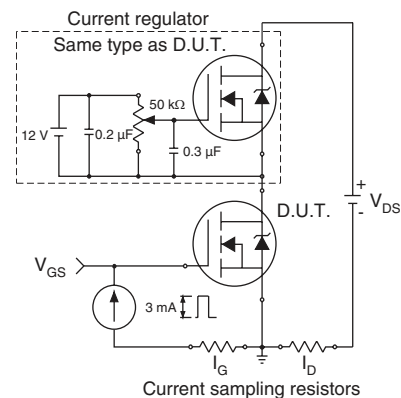


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit

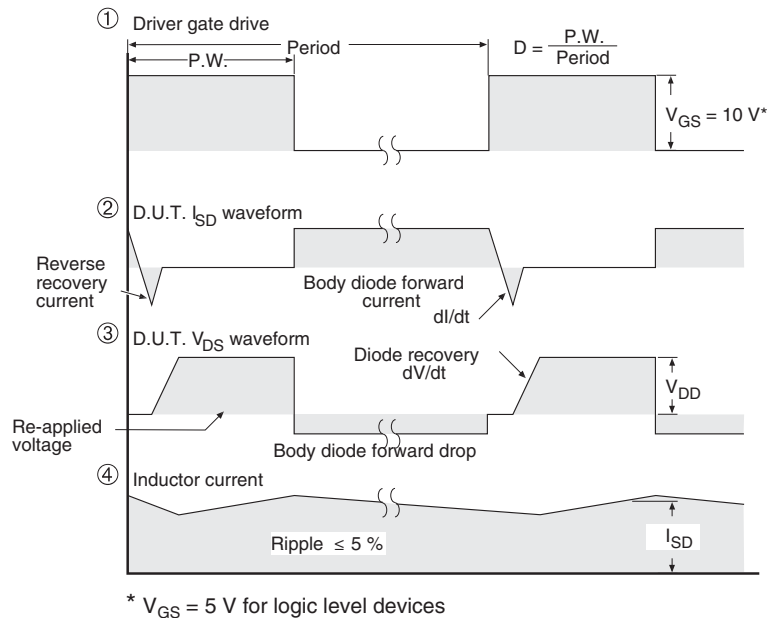
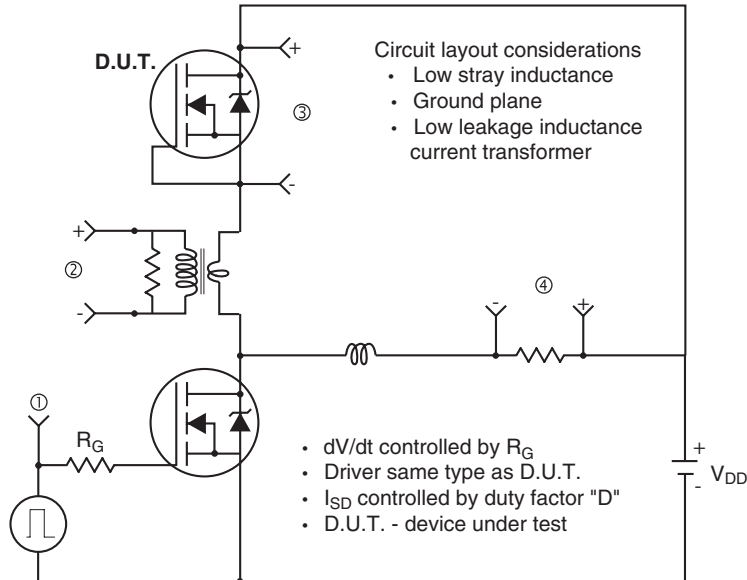


Fig. 14 - For N-Channel

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